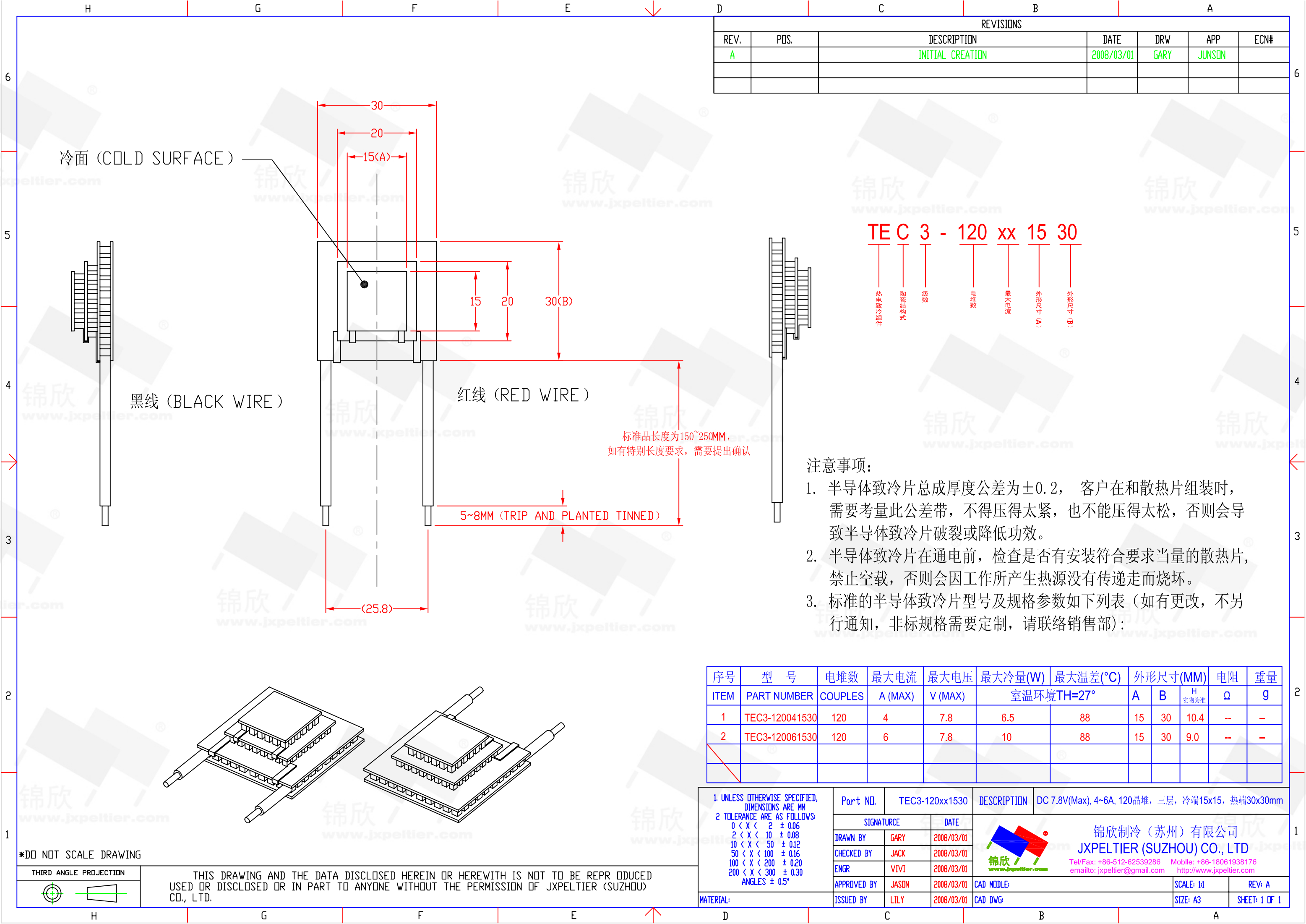



REVISIONS						
REV.	POS.	DESCRIPTION	DATE	DRW	APP	ECN#
A		INITIAL CREATION	2008/03/01	GARY	JUNSON	



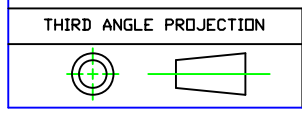
注意事项:

1. 半导体致冷片总成厚度公差为±0.2，客户在和散热片组装时，需要考量此公差带，不得压得太紧，也不能压得太松，否则会导致半导体致冷片破裂或降低功效。
2. 半导体致冷片在通电前，检查是否有安装符合要求当量的散热片，禁止空载，否则会因工作所产生热源没有传递走而烧坏。
3. 标准的半导体致冷片型号及规格参数如下列表（如有更改，不另行通知，非标规格需要定制，请联络销售部）:

序号	型号	电堆数	最大电流	最大电压	最大冷量(W)	最大温差(°C)	外形尺寸(MM)			电阻	重量
ITEM	PART NUMBER	COUPLES	A (MAX)	V (MAX)	室温环境TH=27°		A	B	H 实物为准	Ω	g
1	TEC3-120041530	120	4	7.8	6.5	88	15	30	10.4	--	--
2	TEC3-120061530	120	6	7.8	10	88	15	30	9.0	--	--

1. UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE MM 2. TOLERANCE ARE AS FOLLOWS: 0 < X < 2 ± 0.06 2 < X < 10 ± 0.08 10 < X < 50 ± 0.12 50 < X < 100 ± 0.16 100 < X < 200 ± 0.20 200 < X < 300 ± 0.30 ANGLES ± 0.5°	Part NO.	TEC3-120xx1530		DESCRIPTION	DC 7.8V(Max), 4~6A, 120晶堆, 三层, 冷端15x15, 热端30x30mm			
	SIGNATURE		DATE		 锦欣制冷 (苏州) 有限公司 JXPeltier (SUZHOU) CO., LTD Tel/Fax: +86-512-62539286 Mobile: +86-18061938176 emailto: jxpeltier@gmail.com http://www.jxpeltier.com			
	DRAWN BY	GARY	2008/03/01					
	CHECKED BY	JACK	2008/03/01					
ENGR	VIVI	2008/03/01						
APPROVED BY	JASON	2008/03/01		CAD MDDLE:	SCALE: 1:1		REV: A	
MATERIAL:	ISSUED BY	LILY	2008/03/01	CAD DWG:	SIZE: A3		SHEET: 1 OF 1	

*DO NOT SCALE DRAWING



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